

# AOS Semiconductor Product Reliability Report

# **AOZ8006FI**, rev 1

**Plastic Encapsulated Device** 

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Jun 25, 2007



#### This AOS product reliability report summarizes the gualification result for AOZ8006FI.

Review of the electrical test results confirm that AOZ8006FI pass AOS quality and reliability requirements for product release. The continuous qualification testing and reliability monitoring program ensure that all outgoing products will continue to meet AOS quality and reliability standards.

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#### I. Product Description:

The AOZ8006FI is a transient voltage suppressor array designed to protect high speed data lines from ESD and lightning. The product comes in RoHS compliant, MSOP10 package and is rated over a -40°C to +85°C ambient temperature range.

Absolute Maximum Ratings			
Parameter			
VP-VN	6V		
Peak Pulse Current (Ipp), tp=8/20uS	5A		
Storage Temperature (Ts)	-65°C to +150°C		
ESD Rating per IEC61000-4-2, contact <sup>(1)</sup>	±8kV		
ESD Rating per IEC61000-4-2, air <sup>(2)</sup>	±15kV		
ESD Rating per Human Body Model <sup>(2)</sup>	±8kV		
Junction Temperature (T <sub>j</sub> )	-40°C to +125°C		

Notes:

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- (1) IEC-61000-4-2 discharge with C<sub>Discharge</sub>=150pF, R<sub>Discharge</sub>=330Ω
  (2) Human Body Discharge per MIL-STD-883, Method 3015 C<sub>Discharge</sub>=100pF, R<sub>Discharge</sub>=1.5kΩ

### II. Package and Die Information:

Product ID	AOZ8006FI
Process	UMC 0.5um 5/18V 2P3M process
Package Type	MSOP10
Die	UI001A1_EPI (size: 716 x 616 um)
L/F material	ASM A194FH
Die attach material	Ablestik 8360 epoxy
Die bond wire	Au, 1mil
Mold Material	Sumitomo EME-6600D
Plating Material	Matte Tin



## **III.** Qualification Tests Requirments

- Same package as AOZ8007FI, therefore, the part will be qual. by extension.
- Same package as AOZ8005FI, only difference is the die has BM (back metal) and die attach material is conductive epoxy. Therefore, AOZ8005FI test data can be used for qual. also.

### **IV. Qualification Tests Result**

Test Item	Test Condition	Sample Size	Result	Comment
Pre- Conditioning (qual by extension, using AOZ8007FI data)	Per JESD 22-A113 85 C <sup>0</sup> /85%RH, 3 cyc reflow@260 <sup>°</sup> C	3 lots (82 /lot)	pass	Lots 1 (wafer lot# FN646.52-6, marking: B1002), 82 units, passed pre-con. Lots 2 (wafer lot# FN646.52-6, marking: B1003), 82 units, passed pre-con. Lots 3 (wafer lot# FN646.52-6, marking: B1004), 82 units, passed pre-conditioning.
HTOL (pkg qual burn-in, using AOZ8005FI data)	Per JESD 22-A108_B Vdd=6V Temp = 125 <sup>0</sup> C	3 lots (80 /lot)	pass	Lots 1 (wafer lot# F9AN1.51-01 , marking: Z96R11A ), 80 units, passed 500 hrs . Lots 2 (wafer lot# F9AN1.51-01 , marking: Z96R11B ), 80 units, passed 500 hrs . Lots 3 (wafer lot# F9AN1.51-01 , marking: B1001 ), 82 units, passed 500 hrs .
HTOL (die qual burn-in, using AOZ8005CI data)	Per JESD 22-A108_B Vdd=6V Temp = 125 <sup>0</sup> C	2 lots (80 /lot)	pass	IC Qual by extension using AOZ8005CI which uses the same die. Lots 1 (wafer lot# FN2MT.01-12, marking: AC001), 80 units, passed 500 hrs . Lots 2 (wafer lot# FN646.03-4 marking: AC003), 80 units, passed 168 hrs .
HAST (qual by extension, using AOZ8005FI data)	'130 +/- 2 <sup>⁰</sup> C, 85%RH, 33.3 psi, at VCC min power dissapation	3 lots (60 /lot)	pass	Lots 1 (wafer lot# F9AN1.51-01, marking: Z96R11A), 60 units, passed HAST 100 hr. Lots 2 (wafer lot# F9AN1.51-01, marking: Z96R11B), 60 units, passed HAST 100 h. Lots 3 (wafer lot# F162T, marking: B1001), 60 units, passed HAST 100 h rs.
Temperature Cycle (qual by extension, using AOZ8007FI data)	'-65 <sup>°</sup> C to +150 <sup>°</sup> C, air to air (2cyc/hr)	3 lots (82 /lot)	pass	Lots 1 (wafer lot# FN646.52-6, marking: B1002), 82 units, passed TC 500 cycles. Lots 2 (wafer lot# FN646.52-6, marking: B1003), 82 units, passed TC 500 cycles. Lots 3 (wafer lot# FN646.52-6, marking: B1004), 82 units, passed TC 500 cycles.
Pressure Pot (qual by extension, using AOZ8007FI data)	121C, 15+/-1 PSIG, RH= 100%	3 lots (82 /lot)	pass	Lots 1 (wafer lot# FN646.52-6, marking: B1002), 82 units, passed PCT 96 hrs. Lots 2 (wafer lot# FN646.52-6, marking: B1003), 82 units, passed PCT 96 hrs. Lots 3 (wafer lot# FN646.52-6, marking: B1004), 82 units, passed PCT 96 hrs.
ESD Rating	Per IEC-61000-4-2, contact	3 units	pass	Lot 1 (wafer lot# FN646.52-6,marking: B1001 ), 3 units passed ±8kV
ESD Rating	Per IEC-61000-4-2, air	3 units	pass	Lot 1 (wafer lot# FN646.52-6 , marking: B1001 ), 3 units passed ±15kV
Latch-up (AOZ8005CI data)	Per JESD78A	3 units	pass	Lot 1 (wafer lot# FN646.03-4 ,marking: AC003 ), 3 units passed Latch-up.

The qualification test results confirm that AOZ8006FI pass AOS quality and reliability requirements for product release.



V. Quality Assurance Information Acceptable Quality Level for outgoing inspection: 0.1% for electrical and visual. Guaranteed Outgoing Defect Rate: < 50 ppm Quality Sample Plan: conform to Mil-Std-105D